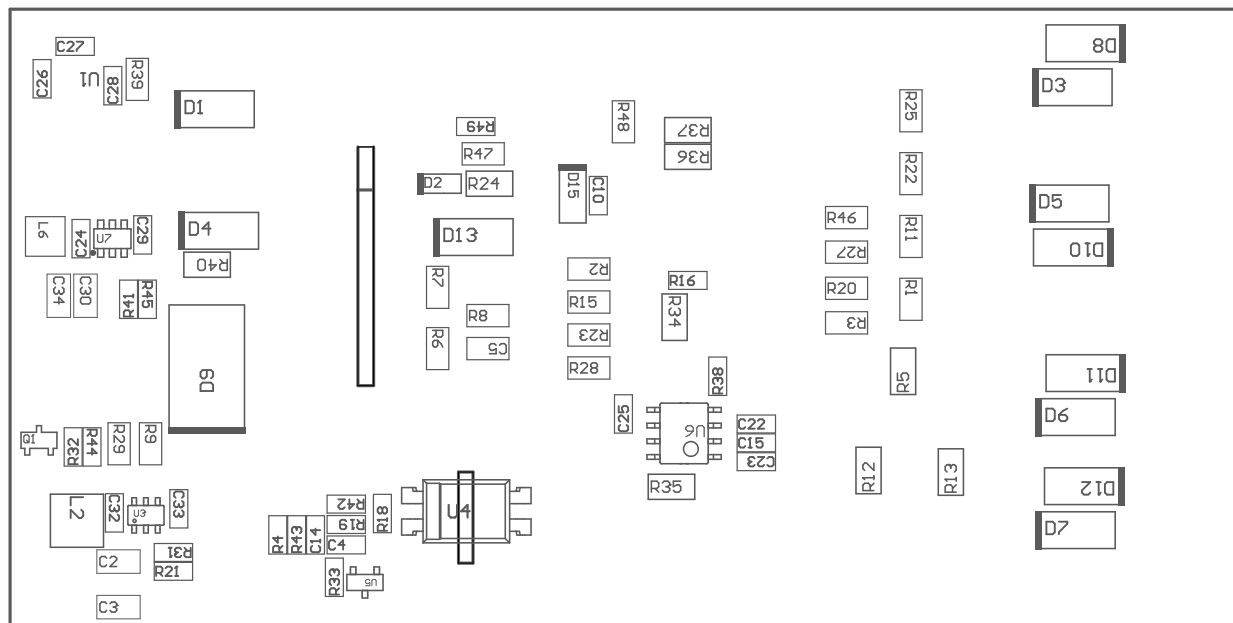


COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.  
 ASSEMBLY VARIANT: 001

PCB VIEWED FROM TOP SIDE	BOARD #: PMP40347	REV: A	SVN REV: Not In VersionControl
	TID #: PMP40347		
PLOT NAME = Top Assembly Drawing	GENERATED : 3/25/2018 10:38:10 PM	TEXAS INSTRUMENTS	



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.  
 ASSEMBLY VARIANT: 001

PCB VIEWED FROM BOTTOM SIDE	BOARD #: PMP40347	REV: A	SVN REV: Not In VersionControl
	TID #: PMP40347		
PLOT NAME = Bottom Assembly Drawing	GENERATED : 3/25/2018	10:38:10 PM	TEXAS INSTRUMENTS

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